

In the Specification

Page 2, please replace the bottom paragraph (lines 18-28) with the following:

Therefore, a need exists for a low-cost, easily constructed identification card having an antenna and chip incorporated into the body of the card, which protects these electronic components from damage. Applicants invention relates to a unique structure capable of protecting the IC chip and antenna. Applicants' invention contains two relatively shock-absorbing layers, which may contain indicia. In an embodiment, two rigid outer laminate layers encase the relatively shock absorbing layers, adding structural support and protection. Applicants' card differs from the prior art in that in the prior art, normally rigid materials are used throughout the card, thus permitting external stresses and bending to damage the delicate IC chip and antenna. In applicants' improved design, rigid outer layers disseminate external forces over a broad area of compliant layers, thus protecting the electronic components.

Page 4, Please replace the 2nd full paragraph and the 3rd paragraph with the following paragraphs:

~~"In order to~~ To minimize the risk of damage to the fragile electronic components, preferably alkyd resin spids containing an anti-binding agent are printed onto one side of the shrunken core sheet on the side opposite from the indicia. Polyester epoxy material containing a release agent, acrylate epoxy material containing a release agent, and vinyl acetate epoxy material containing a release agent are examples of an alkyd resin spid used in at least some embodiments of the invention. These spids may be printed in any pattern; however, in an embodiment they are printed onto the core in a "racetrack" or oval pattern. Antennae, typically silver-epoxy antennae, are then printed onto the spids in a matching pattern. Integrated circuit chips are attached to solder bumps on the antennae in the conventional manner.

The core layer with attached antennae and IC chips is then bonded to a bottom sheet of printable, silica-filled polyolefin with an adhesive layer. The adhesive layer may be composed of a number of commercially available adhesives; however, very desirably it is composed of a

co-polyester based adhesive such as the adhesive sold commercially by Transilwrap, Inc., Richmond, IN under the name ~~Transilwrap®~~ TRANSILWRAP TXP(3). Because IC chips are typically much thicker than the antennae, preferably recesses are cut into the TXP(3) adhesive layer to accommodate the IC chips. By removing a section of the adhesive, the identification card will be of uniform thickness. Because recesses were cut in this TXP(3) adhesive layer, ~~in order~~ to bond the IC chip to the bottom layer, an additional layer of adhesive is required. Although this adhesive may comprise any suitable adhesive, in the preferred embodiment it is a carboxylated polyethylene hot melt adhesive such as that manufactured by Transilwrap, Inc. and sold under the name ~~Transilwrap®~~ TRANSILWRAP KRTY. This adhesive is applied to the bottom layer prior to assembly of the card and serves to bind the IC chip to the bottom layer. During lamination of the identification card, the TXP(s) adhesive layer will flow freely thus adhering the core

On page 8, Please replace the 1st full paragraph with the following paragraph:

Figure 1 of the accompanying drawings shows a schematic cross-section through an embodiment of an identification card of the present invention. The document comprises a core layer 12 and a bottom layer 14, both formed of an opaque white reflective polyolefin (preferably the aforementioned TESLIN® sheet). One side of the core layer and one side of the bottom are printed with fixed indicia 16. Sandwiched between the core layer 12 and the bottom layer 14 are an antenna 18 connected to an integrated circuit chip 20. An alkyd resin spid 22 lies beneath the core layer 12 and the antenna 18. An adhesive layer 24 (preferably KRTY) is applied to the bottom layer 14 on the side facing the core layer 12. The bottom layer and the core layer 12 are joined with an adhesive layer 26 (preferably TXP(3)). Recesses are cut into the adhesive layer 26 to accommodate the integrated circuit chip 320.

On page 8, please replace the last paragraph (final 5 lines on the page) with the following:

Figure 2 of the accompanying drawings shows a schematic cross-section through an alternate embodiment of an identification card of the present invention. The document, generally designated 10, comprises a core layer 12 and a bottom layer 14, both formed of an opaque white reflective polyolefin (preferably the aforementioned TESLIN® sheet). Opposed sides of the core layer and the bottom